when the module is placed in an insertion/withdrawal position while allowing the pad to shift in a direction of insertion/withdrawal when the module is in the insertion/withdrawal position in which the rear side of the module is at a higher level than in the connection position, and a lateral supporting part that extends rearward from the receiving part to support a left side, a right side and a bottom of the module in the connection position; and

a metallic cover including a first connection means for connection to said receiving part of said connector body and a second connection means for connection to said lateral supporting part,

wherein said metallic cover is put over and is engaged to the connector body to sandwich the module between said metallic cover and the supporting part to thereby maintain the module in the connection position.

20. (Twice Amended) A connector for a module that connects the module, the module having a semiconductor chip mounted on a rectangular board and a conductive pad on a front side of the board, to a printed circuit board in a position wherein a plane of the board is substantially parallel to the printed circuit board,

said connector comprising:

a connector body having a receiving part that extends along the front side of the module being in a connection position, and a groove provided in a rear face thereof into which the front side of the module is inserted, said groove having contacts provided therein which contact the conductive pad on both a top surface and a bottom surface of the module when the module is placed in an insertion/withdrawal position while allowing the pad to shift in a direction of insertion/withdrawal when the module is in the insertion/withdrawal position in which the rear side of the module is at a higher level than in the connection position, and a supporting part that extends rearward from the receiving part to support a left side, a right side and a bottom of the module in the connection position;

a metallic cover that is put over and is engaged with the connector body to sandwich the module between said metallic cover and the supporting part to thereby maintain the module in the connection position, said metallic cover including a window for exposing the semiconductor chip when the module is placed in the connection position, and a heat sink secured to said metallic cover and contacts the semiconductor chip to dissipate heat therefrom,

wherein at least one of said metallic cover and said heat sink covers said contacts and the conductive pad to exhibit a shielding function against electromagnetic waves.